502297116 04/03/2013

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsiang-Wei Lin	03/28/2013
Chia-Ho Chen	03/28/2013
Bo-Hung Lin	03/28/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company Limited
Street Address:	No. 8, Li-Hsin Road 6
Internal Address:	Hsin-Chu Science Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13855939

OP $40.00 13855939

CORRESPONDENCE DATA

Fax Number: 2163733450
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 2166540090
Email: docketing@cooperlegalgroup.com
Correspondent Name: Cooper Legal Group LLC
Address Line 1: 6505 Rockside Road Suite 330
Address Line 4: Independence, OHIO 44131

ATTORNEY DOCKET NUMBER:	TSMC 2012-1374
NAME OF SUBMITTER:	David J. Stein
Signature:	/David J. Stein/

Date:	04/03/2013

Total Attachments: 2
source=Assignment#page1.tif
source=Assignment#page2.tif

TSMC 2012-1374

ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Hsiang-Wei Lin	Chia-Ho Chen	Bo-Hung Lin
New Taipei City, TW	Zhubei City, TW	Kaohsiung City, TW

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Hsiang-Wei Lin, Chia-Ho Chen and Bo-Hung Lin, by these present do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

DIRECTING PLASMA DISTRIBUTION IN PLASMA-ENHANCED CHEMICAL VAPOR DEPOSITION

for which application for United States Letters Patent has been filed on ______________ under Serial No.___________, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts

TSMC 2012-1374

relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

Hsiang-Wei Lin	2013. 3. 28
Inventor's Signature	Date
Hsiang-Wei Lin	
Printed Name in English	

Chiaho Chen	2013. 3. 28
Inventor's Signature	Date
Chia-Ho Chen	
Printed Name in English	

Bo-Hung Lin	2013. 03. 28
Inventor's Signature	Date
Bo-Hung Lin	
Printed Name in English	